

# Preliminary MSD50N03

## N-Channel Logic Level Enhancement Mode Power MOSFET

### Description

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $r_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

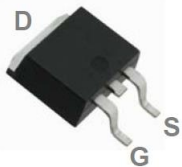
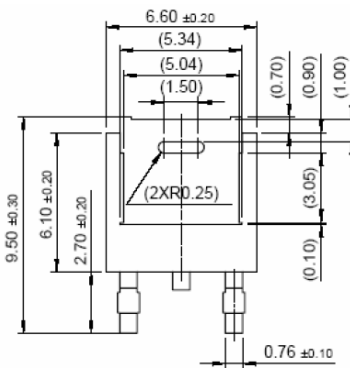
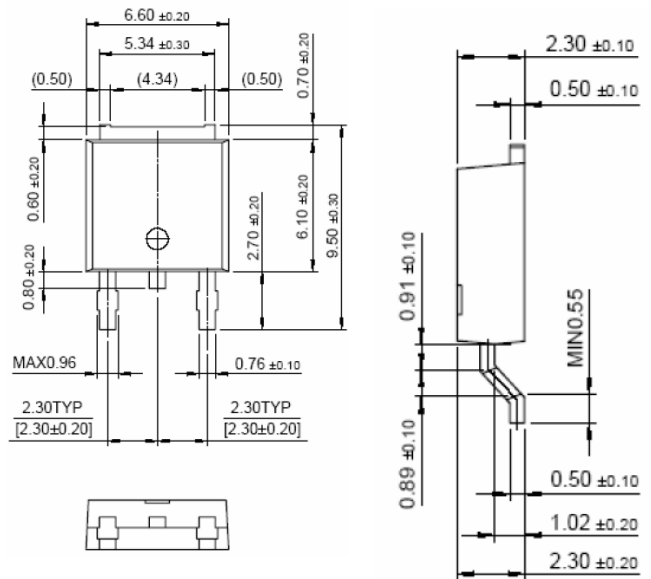
### Features

- $V_{DS}=30V$ ,  $I_D=50A$ ,  $R_{DS(ON)}=9m\Omega$
- Low Gate Charge
- Repetitive Avalanche Rated
- Simple Drive Requirement
- Fast Switching Characteristic
- RoHS compliant package

### Packing & Order Information

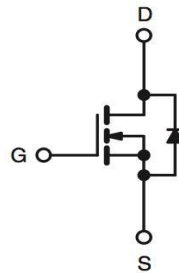
Part No./ T : 2,500/Reel

Part No./ R : 80/Tube , 4,000/Box



**RoHS  
COMPLIANT**

### Graphic symbol



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

#### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Continuous Drain Current @ $T_C=25^\circ C$	50	A
	Continuous Drain Current @ $T_C=100^\circ C$	35	A

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### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
$I_{DM}^{*1}$	Pulsed Drain Current	140	A
$I_{AS}$	Avalanche Current	37.5	A
$E_{AS}$	Avalanche Energy @ L=0.1mH , $I_D = 37.5$ A , $R_g = 25 \Omega$	70	mJ
$E_{AR}^{*2}$	Repetitive Avalanche Energy @ L=0.05mH	15	mJ
$P_D$	Power Dissipation (TC=25°C)	60	W
	Power Dissipation (TC=100°C)	32	W
$T_J/T_{STG}$	Operating Junction and Storage Temperature	-55 to +150	°C

#### Note:

100% UIS testing in condition of  $V_D=15V$ ,  $L=0.1mH$ ,  $V_G=10V$ ,  $I_L=25A$ , Rated  $V_{DS}=25V$  N-CH

\*1. Pulse width limited by maximum junction temperature

\*2. Duty cycle  $\leq 1\%$

### Thermal Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Maximum	Units
$R_{thjc}$	Typical thermal resistance	2.5	°C/W
$R_{\theta JA}$	Typical thermal resistance	75	

### Static Characteristics

Symbol	Test Conditions	Min	Typ.	Max.	Units
$V_{GS}$	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	1.0	1.7	3.0	V
$*R_{DS(ON)}$	$V_{GS} = 10$ V , $I_D = 25$ A	--	75	9	mΩ
	$V_{GS} = 5$ V , $I_D = 20$ A	--	12	15	
$BV_{DSS}$	$V_{GS} = 0$ V , $I_D = 250 \mu A$	30	--	--	V
$I_{DSS}$	$V_{DS} = 24$ V , $V_{GS} = 0$ V	--	--	1	uA
	$V_{DS} = 20$ V , $V_{GS} = 0$ V , $T_j = 125^\circ C$	--	--	25	
$I_{D(ON)}$	$V_{DS} = 10$ V , $V_{GS} = 10$ V	50	--	--	A
$I_{GSS}$	$V_{DS} = \pm 20$	--	--	$\pm 100$	nA
$G_{FS}$	$V_{DS} = 5$ V , $V_{GS} = 20$ V	--	20	--	S

### Dynamic Characteristics

Symbol	Test Conditions	Min	Typ.	Max.	Units
$C_{ISS}$	$V_{DS} = 15$ V , $V_{GS} = 0$ V , $F = 1.0MHz$	--	2020	--	pF
$C_{OSS}$		--	275	--	pF
$C_{RSS}$		--	160	--	pF

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### Dynamic Characteristics

Symbol	Test Conditions	Min	Typ.	Max.	Units
$t_{d(on)}$	$V_{DS} = 150\text{ V}$ , $I_D = 25\text{ A}$ , $R_G = 2.7\ \Omega$ , $V_{GS} = 10\text{ V}$ $R_D = 0.6\ \Omega$	--	10	--	ns
$t_r$		--	8	--	ns
$t_{d(off)}$		--	30	--	ns
$t_f$		--	5	--	ns
$Q_g(V_{GS} = 10\text{ V})$	$V_{DS} = 15\text{ V}$ , $I_D = 25\text{ A}$ , $V_{GS} = 10\text{ V}$	--	23	--	nC
$Q_g(V_{GS} = 5\text{ V})$		--	13	--	nC
$Q_{gs}$		--	4.7	--	nC
$Q_{gd}$		--	7.4	--	nC
$R_g$	$V_{GS} = 15\text{ mV}$ , $V_{DS} = 0$ , $f = 1\text{ MHz}$	--	1.7	--	$\Omega$

### Source-Drain Diode Characteristics

Symbol	Test Conditions	Min	Typ.	Max.	Units
$I_S$		--	--	50	A
$I_{SM}$		--	--	140	
$V_{SD}$	$I_F = I_S$ , $V_{GS} = 0\text{ V}$	--	--	1.3	V
$t_{rr}$	$I_F = I_S$ , $V_{GS} = 0\text{ V}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$	--	22	--	ns
IRM(REC)		--	180	--	A
$Q_{rr}$		--	12	--	nC

\*Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$

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